AMD Xilinx - XC2V1000-4FG256I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1280
Number of Logic Elements/Cells	-
Total RAM Bits	737280
Number of I/O	172
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2v1000-4fg256i

Table 4: **LVTTL and LVCMOS Programmable Currents (Sink and Source)**

SelectI/O-Ultra	Programmable Current (Worst-Case Guaranteed Minimum)						
LVTTL	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS33	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS25	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS18	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	n/a
LVCMOS15	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	n/a

Figure 6 shows the SSTL2, SSTL3, and HSTL configurations. HSTL can sink current up to 48 mA. (HSTL IV)

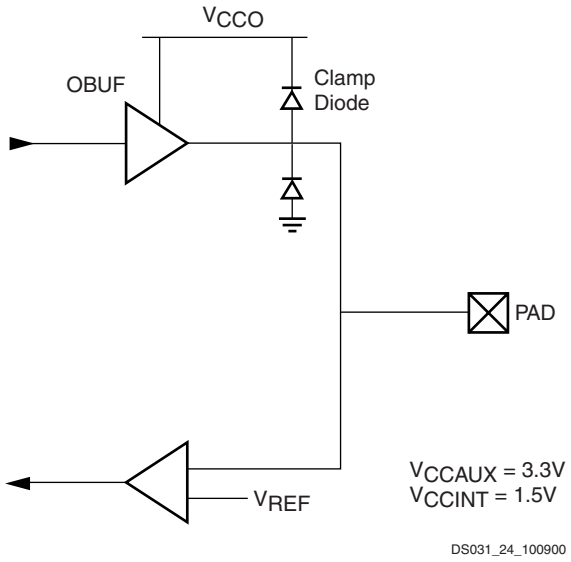


Figure 6: **SSTL or HSTL SelectI/O-Ultra Standards**

All pads are protected against damage from electrostatic discharge (ESD) and from over-voltage transients. Virtex-II uses two memory cells to control the configuration of an I/O as an input. This is to reduce the probability of an I/O configured as an input from flipping to an output when subjected to a single event upset (SEU) in space applications.

Prior to configuration, all outputs not involved in configuration are forced into their high-impedance state. The pull-down resistors and the weak-keeper circuits are inactive. The dedicated pin HSWAP_EN controls the pull-up resistors prior to configuration. By default, HSWAP_EN is set high, which disables the pull-up resistors on user I/O pins. When HSWAP_EN is set low, the pull-up resistors are activated on user I/O pins.

All Virtex-II IOBs support IEEE 1149.1 compatible Boundary-Scan testing.

Input Path

The Virtex-II IOB input path routes input signals directly to internal logic and / or through an optional input flip-flop or latch, or through the DDR input registers. An optional delay element at the D-input of the storage element eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the Virtex-II device, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signaling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF}. The need to supply V_{REF} imposes constraints on which standards can be used in the same bank. See I/O banking description.

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output and / or the 3-state signal can be routed to the buffer directly from the internal logic or through an output / 3-state flip-flop or latch, or through the DDR output / 3-state registers.

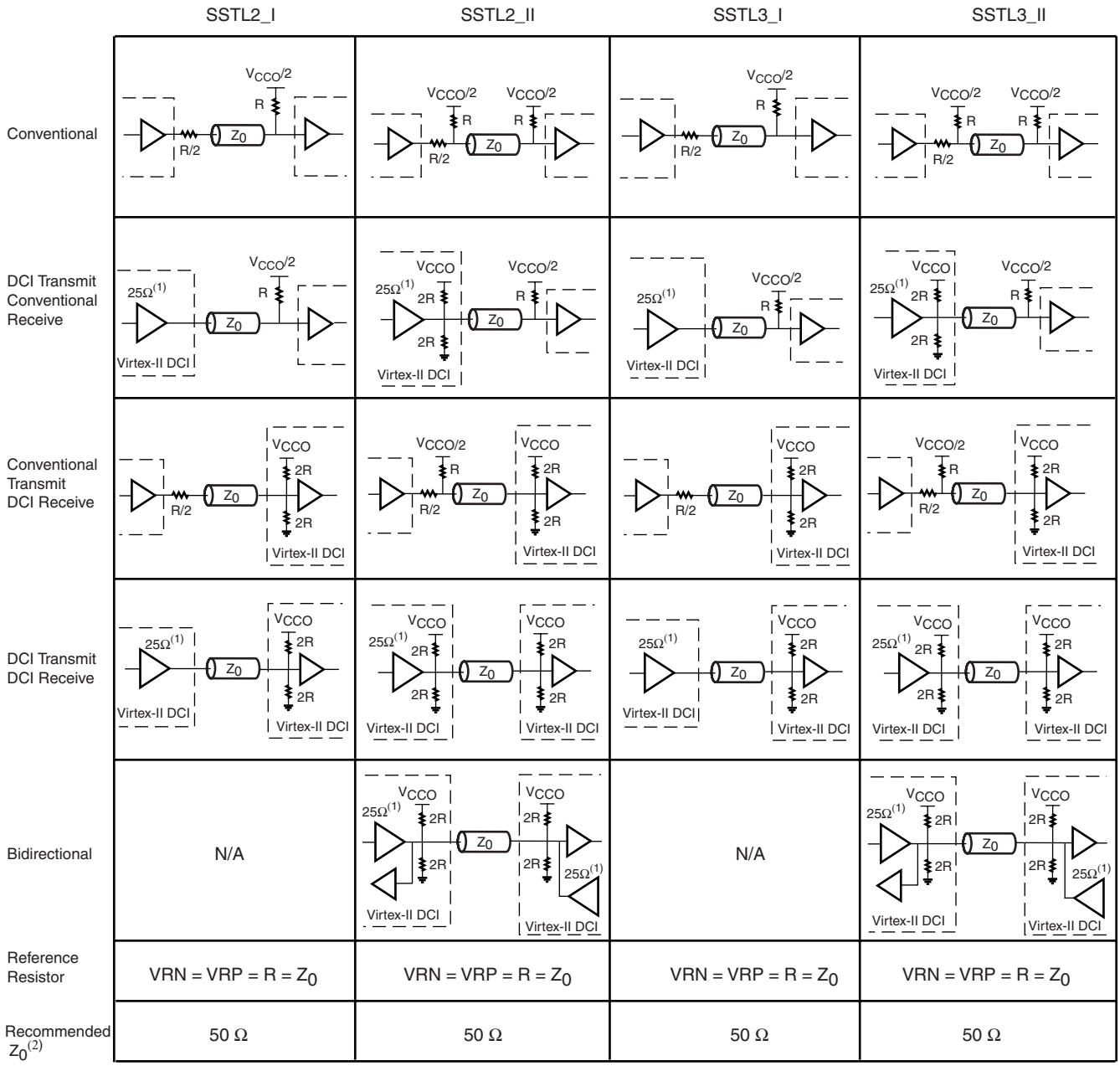
Each output driver can be individually programmed for a wide range of low-voltage signaling standards. In most signaling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in the same bank. See I/O banking description.

I/O Banking

Some of the I/O standards described above require V_{CCO} and V_{REF} voltages. These voltages are externally supplied and connected to device pins that serve groups of IOB blocks, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

Eight I/O banks result from dividing each edge of the FPGA into two banks, as shown in Figure 7 and Figure 8. Each bank has multiple V_{CCO} pins, all of which must be connected to the same voltage. This voltage is determined by the output standards in use.

Figure 12 provides examples illustrating the use of the SSTL2_I_DCI, SSTL2_II_DCI, SSTL3_I_DCI, and SSTL3_II_DCI I/O standards. For a complete list, see the **Virtex-II Platform FPGA User Guide**.



Notes:
1. The SSTL-compatible 25Ω series resistor is accounted for in the DCI buffer, and it is not DCI controlled.
2. Z_0 is the recommended PCB trace impedance.

DS031_65b_112502

Figure 12: **SSTL DCI Usage Examples**

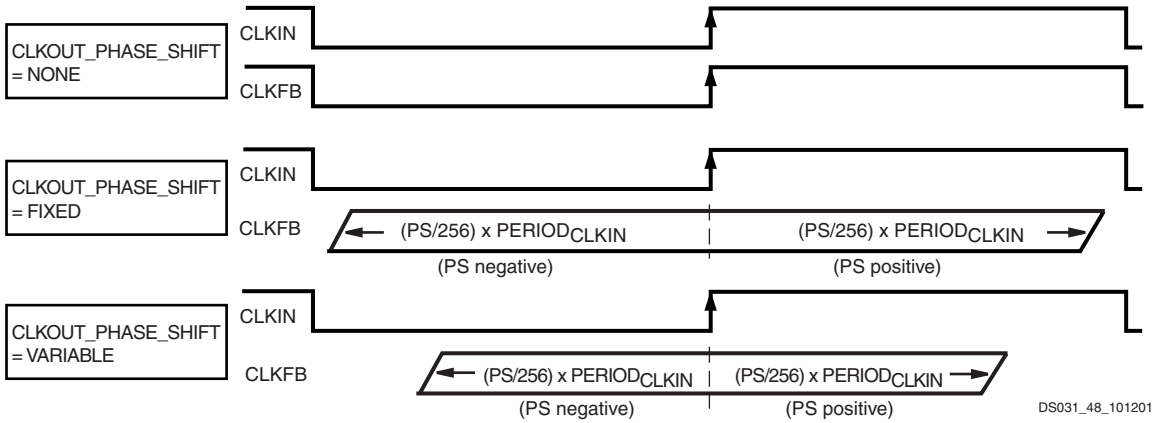


Figure 46: **Fine-Phase Shifting Effects**

Table 22 lists fine-phase shifting control pins, when used in variable mode.

Table 22: **Fine-Phase Shifting Control Pins**

Control Pin	Direction	Function
PSINCDEC	in	Increment or decrement
PSEN	in	Enable ± phase shift
PSCLK	in	Clock for phase shift
PSDONE	out	Active when completed

Two separate components of the phase shift range must be understood:

- PHASE_SHIFT attribute range
- FINE_SHIFT_RANGE DCM timing parameter range

The PHASE_SHIFT attribute is the numerator in the following equation:

Phase Shift (ns) = (PHASE_SHIFT/256) * $PERIOD_{CLKIN}$

The full range of this attribute is always -255 to +255, but its practical range varies with CLKIN frequency, as constrained by the FINE_SHIFT_RANGE component, which represents the total delay achievable by the phase shift delay line. Total delay is a function of the number of delay taps used in the circuit. Across process, voltage, and temperature, this absolute range is guaranteed to be as specified under DCM Timing Parameters in Module 3.

Absolute range (fixed mode) = ± FINE_SHIFT_RANGE

Absolute range (variable mode) = ± FINE_SHIFT_RANGE/2

The reason for the difference between fixed and variable modes is as follows. For variable mode to allow symmetric, dynamic sweeps from -255/256 to +255/256, the DCM sets the "zero phase skew" point as the middle of the delay line, thus dividing the total delay line range in half. In fixed mode, since the PHASE_SHIFT value never changes after configuration, the entire delay line is available for insertion into either the CLKIN or CLKFB path (to create either positive or negative skew).

Taking both of these components into consideration, the following are some usage examples:

- If $PERIOD_{CLKIN}$ = 2 * FINE_SHIFT_RANGE, then PHASE_SHIFT in fixed mode is limited to ± 128, and in variable mode it is limited to ± 64.
- If $PERIOD_{CLKIN}$ = FINE_SHIFT_RANGE, then PHASE_SHIFT in fixed mode is limited to ± 255, and in variable mode it is limited to ± 128.
- If $PERIOD_{CLKIN} \leq 0.5$ * FINE_SHIFT_RANGE, then PHASE_SHIFT is limited to ± 255 in either mode.

Operating Modes

The frequency ranges of DCM input and output clocks depend on the operating mode specified, either low-frequency mode or high-frequency mode, according to Table 23. (For actual values, see Virtex-II Switching Characteristics in Module 3). The CLK2X, CLK2X180, CLK90, and CLK270 outputs are not available in high-frequency mode.

High or low-frequency mode is selected by an attribute.

Table 23: **DCM Frequency Ranges**

Output Clock	Low-Frequency Mode		High-Frequency Mode	
	CLKIN Input	CLK Output	CLKIN Input	CLK Output
CLK0, CLK180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_1X_HF
CLK90, CLK270	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	NA	NA
CLK2X, CLK2X180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_2X_LF	NA	NA
CLKDV	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_DV_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_DV_HF
CLKFX, CLKFX180	CLKIN_FREQ_FX_LF	CLKOUT_FREQ_FX_LF	CLKIN_FREQ_FX_HF	CLKOUT_FREQ_FX_HF

Table 2: **Recommended Operating Conditions**

Symbol	Description	Temperature Range and Grade		Min	Max	Units
V_{CCINT}	Internal supply voltage relative to GND	T_J = 0 °C to +85°C	Commercial	1.425	1.575	V
		T_J = –40°C to +100°C	Industrial	1.425	1.575	V
V_{CCAUX}	Auxiliary supply voltage relative to GND	T_J = 0 °C to +85°C	Commercial	3.135	3.465	V
		T_J = –40°C to +100°C	Industrial	3.135	3.465	V
V_{CCO}	Supply voltage relative to GND	T_J = 0 °C to +85°C	Commercial	1.2	3.6	V
		T_J = –40°C to +100°C	Industrial	1.2	3.6	V
V_{BATT}(1)	Battery voltage relative to GND	T_J = 0 °C to +85°C	Commercial	1.0	3.6	V
		T_J = –40°C to +100°C	Industrial	1.0	3.6	V

Notes:
1. If battery is not used, connect V_{BATT} to GND or V_{CCAUX}.
2. Recommended maximum voltage droop for V_{CCAUX} is 10 mV/ms.
3. The thresholds for Power On Reset are V_{CCINT} > 1.2V, V_{CCAUX} > 2.5V, and V_{CCO} (Bank 4) > 1.5 V.
4. Limit the noise at the power supply to be within 200 mV peak-to-peak.
5. For power bypassing guidelines, see XAPP623 at www.xilinx.com.

Table 3: **DC Characteristics Over Recommended Operating Conditions**

Symbol	Description	Device	Min	Max	Units
V_{DRINT}	Data retention V_{CCINT} voltage	All	1.2		V
V_{DRI}	Data retention V_{CCAUX} voltage	All	2.5		V
I_{REF}	V_{REF} current per pin	All	–10	+10	µA
I_L	Input leakage current	All	–10	+10	µA
C_{IN}	Input capacitance	All		10	pF
I_{RPU}	Pad pull-up (when selected) @ V_{IN} = 0 V, V_{CCO} = 3.3 V (sample tested)	All	Note (1)	250	µA
I_{RPD}	Pad pull-down (when selected) @ V_{IN} = 3.6 V (sample tested)	All	Note (1)	250	µA
I_{BATT}	Battery supply current	All	(Note 2)		nA

Notes:
1. Internal pull-up and pull-down resistors guarantee valid logic levels at unconnected input pins. These pull-up and pull-down resistors do not guarantee valid logic levels when input pins are connected to other circuits.
2. Battery supply current (I_{BATT}):

	Device Unpowered	Device Powered	Units
25°C:	< 50	< 10	nA
85°C:	N/A	< 10	nA

Table 4: **Quiescent Supply Current**

Symbol	Description	Device	Min	Typical	Max	Units
I_{CCINTQ}	Quiescent V_{CCINT} supply current	XC2V40		3	125	mA
		XC2V80		5	125	
		XC2V250		8	150	
		XC2V500		10	200	
		XC2V1000		12	250	
		XC2V1500		15	350	
		XC2V2000		20	400	
		XC2V3000		27	500	
		XC2V4000		35	650	
		XC2V6000		45	800	
		XC2V8000		60	1100	
I_{CCOQ}	Quiescent V_{CCO} supply current(1,2)	XC2V40		1	2	mA
		XC2V80		1	2	
		XC2V250		1	2	
		XC2V500		1	2	
		XC2V1000		1	2	
		XC2V1500		2	4	
		XC2V2000		2	4	
		XC2V3000		2	4	
		XC2V4000		2	4	
		XC2V6000		2	4	
		XC2V8000		2	4	
I_{CCAUXQ}	Quiescent V_{CCAUX} supply current(1,2)	XC2V40		5	25	mA
		XC2V80		5	25	
		XC2V250		5	25	
		XC2V500		5	25	
		XC2V1000		5	25	
		XC2V1500		7.5	50	
		XC2V2000		7.5	50	
		XC2V3000		10	75	
		XC2V4000		10	75	
		XC2V6000		12.5	100	
		XC2V8000		12.5	100	

Notes:
1. With no output current loads, no active input pull-up resistors, all I/O pins are 3-state and floating.
2. If DCI or differential signaling is used, more accurate values can be obtained by using the Power Estimator or XPOWER™.
3. Data are retained even if V_{CCO} drops to 0 V.
4. Values specified for quiescent supply current parameters are Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.25.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device operation. The actual current consumed depends on the power-on ramp rate of the power supply.

The V_{CCINT}, V_{CCAUX}, and V_{CCO} power supplies shall each ramp on, monotonically, no faster than 200 µs and no slower than 50 ms. Ramp on is defined as: 0 V_{DC} to minimum supply voltages.

Table 5 shows the minimum current required by Virtex-II devices for proper power on and configuration.

Power supplies can be turned on in any sequence.(1)

If any V_{CCO} bank powers up before V_{CCAUX}, then each bank draws up to 300 mA, worst case, until the V_{CCAUX} powers up.(2) This does not harm the device. If the current is limited to the minimum value above, or larger, the device powers on properly after all three supplies have passed through their power-on reset threshold voltages.

Once initialized and configured, use the power calculator to estimate current drain on these supplies.

Notes:
1. If the V_{CCINT} ramp rate is longer than 10 ms, then V_{CCINT} must be applied before V_{CCO} and V_{CCAUX}. The device will not be damaged if this requirement is violated, but configuration will probably fail.
2. The 300 mA is transient current (peak); it eventually disappears even if V_{CCAUX} does not power up.

IOB Input Switching Characteristics Standard Adjustments

Table 15 gives all standard-specific data input delay adjustments.

Table 15: **IOB Input Switching Characteristics Standard Adjustments**

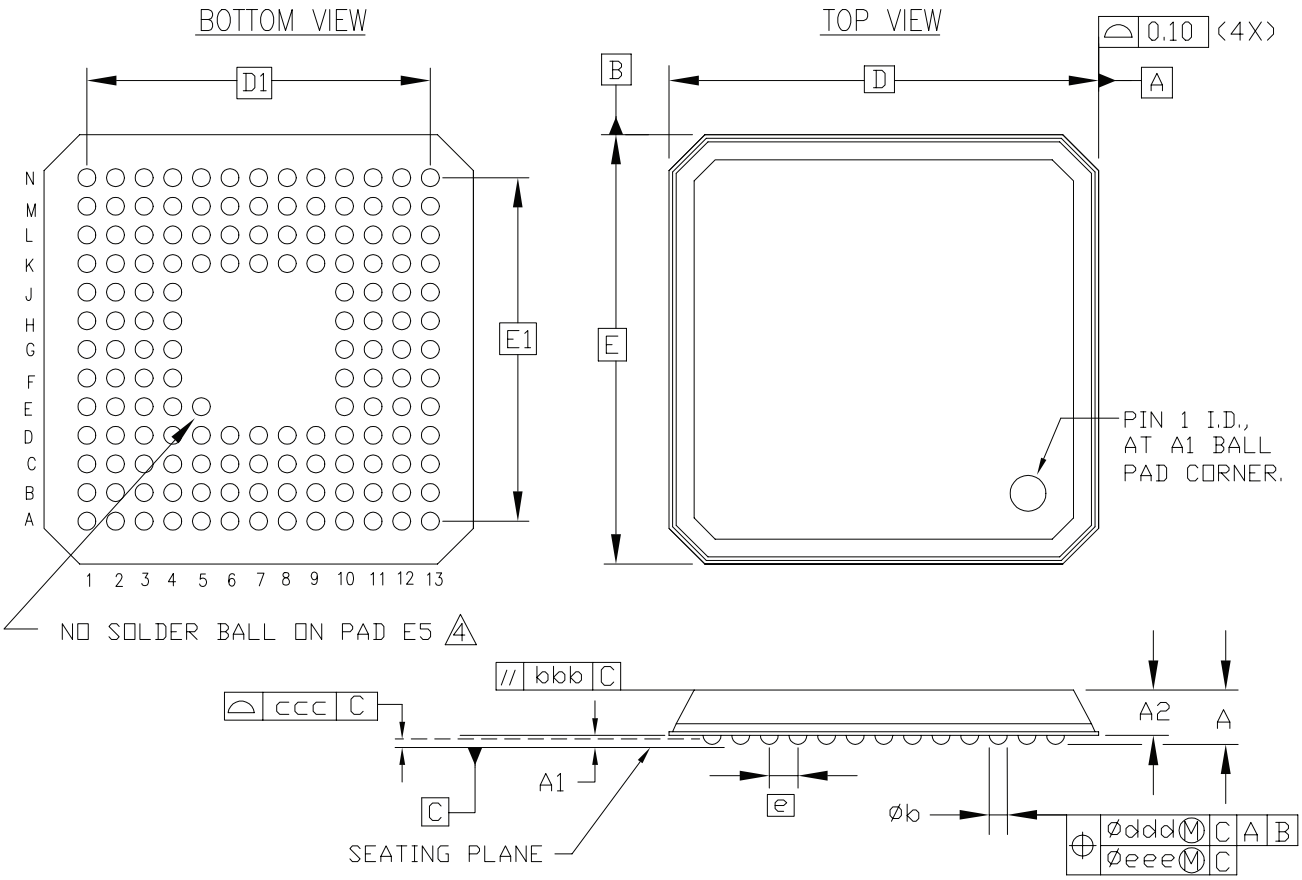
Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-6	-5	-4	
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL	T_{ILVTTL}	0.00	0.00	0.00	ns
LVCMOS (Low-Voltage CMOS), 3.3V	LVCMOS33	$T_{ILVCMOS33}$	0.00	0.00	0.00	ns
LVCMOS, 2.5V	LVCMOS25	$T_{ILVCMOS25}$	0.11	0.11	0.12	ns
LVCMOS, 1.8V	LVCMOS18	$T_{ILVCMOS18}$	0.42	0.43	0.49	ns
LVCMOS, 1.5V	LVCMOS15	$T_{ILVCMOS15}$	0.98	1.00	1.15	ns
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	T_{ILVDS_25}	0.60	0.60	0.69	ns
LVDS, 3.3V	LVDS_33	T_{ILVDS_33}	0.60	0.60	0.69	ns
LVDSEXT (Extended Mode), 2.5V	LVDSEXT_25	$T_{ILVDSEXT\_25}$	0.68	0.69	0.79	ns
LVDSEXT, 3.3V	LVDSEXT_33	$T_{ILVDSEXT\_33}$	0.56	0.56	0.65	ns
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	T_{IULVDS_25}	0.48	0.49	0.56	ns
BLVDS (Bus LVDS), 2.5V	BLVDS_25	T_{IBLVDS_25}	0.68	0.69	0.79	ns
LDT (HyperTransport), 2.5V	LDT_25	T_{ILDT_25}	0.48	0.49	0.56	ns
LVPECL (Low-Voltage Positive Electron-Coupled Logic), 3.3V	LVPECL_33	$T_{ILVPECL\_33}$	0.60	0.60	0.69	ns
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	T_{IPCI33_3}	0.00	0.00	0.00	ns
PCI, 66 MHz, 3.3V	PCI66_3	T_{IPCI66_3}	0.00	0.00	0.00	ns
PCI-X, 133 MHz, 3.3V	PCIX	T_{IPCIX}	0.00	0.00	0.00	ns
GTL (Gunning Transceiver Logic)	GTL	T_{IGTL}	0.42	0.42	0.48	ns
GTL Plus	GTLP	T_{IGTLP}	0.42	0.42	0.48	ns
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	T_{IHSTL_I}	0.42	0.42	0.48	ns
HSTL, Class II	HSTL_II	T_{IHSTL_II}	0.42	0.42	0.48	ns
HSTL, Class III	HSTL_III	T_{IHSTL_III}	0.42	0.42	0.48	ns
HSTL, Class IV	HSTL_IV	T_{IHSTL_IV}	0.42	0.42	0.48	ns
HSTL, Class I, 1.8V	HSTL_I_18	$T_{IHSTL\_I\_18}$	0.42	0.42	0.48	ns
HSTL, Class II, 1.8V	HSTL_II_18	$T_{IHSTL\_II\_18}$	0.42	0.42	0.48	ns
HSTL, Class III, 1.8V	HSTL_III_18	$T_{IHSTL\_III\_18}$	0.42	0.42	0.48	ns
HSTL, Class IV, 1.8V	HSTL_IV_18	$T_{IHSTL\_IV\_18}$	0.42	0.42	0.48	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	$T_{ISSTL18\_I}$	0.42	0.42	0.48	ns
SSTL, Class II, 1.8V	SSTL18_II	$T_{ISSTL18\_II}$	0.42	0.42	0.48	ns
SSTL, Class I, 2.5V	SSTL2_I	T_{ISSTL2_I}	0.42	0.42	0.48	ns
SSTL, Class II, 2.5V	SSTL2_II	T_{ISSTL2_II}	0.42	0.42	0.48	ns
SSTL, Class I, 3.3V	SSTL3_I	T_{ISSTL3_I}	0.35	0.35	0.40	ns
SSTL, Class II, 3.3V	SSTL3_ II	T_{ISSTL3_II}	0.35	0.35	0.40	ns
AGP-2X/AGP (Accelerated Graphics Port)	AGP	T_{IAGP}	0.35	0.35	0.40	ns
LVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	T_{ILVDCI_33}	0.00	0.00	0.00	ns
LVDCI, 2.5V	LVDCI_25	T_{ILVDCI_25}	0.11	0.11	0.12	ns
LVDCI, 1.8V	LVDCI_18	T_{ILVDCI_18}	0.42	0.43	0.49	ns
LVDCI, 1.5V	LVDCI_15	T_{ILVDCI_15}	0.98	1.00	1.14	ns

Table 4: **Virtex-II Pin Definitions *(Continued)***

Pin Name	Direction	Description
PROG_B	Input	Active Low asynchronous reset to configuration logic. This pin has a permanent weak pull-up resistor.
DONE	Input/Output	DONE is a bidirectional signal with an optional internal pull-up resistor. As an output, this pin indicates completion of the configuration process. As an input, a Low level on DONE can be configured to delay the start-up sequence.
M2, M1, M0	Input	Configuration mode selection.
HSWAP_EN	Input	Enable I/O pull-ups during configuration.
TCK	Input	Boundary Scan Clock.
TDI	Input	Boundary Scan Data Input.
TDO	Output	Boundary Scan Data Output.
TMS	Input	Boundary Scan Mode Select.
PWRDWN_B	Input *(unsupported)*	Active Low power-down pin (unsupported). *Driving this pin Low can adversely affect device operation and configuration.* PWRDWN_B is internally pulled High, which is its default state. It does not require an external pull-up.
Other Pins		
DXN, DXP	N/A	Temperature-sensing diode pins (Anode: DXP, Cathode: DXN).
V_{BATT}	Input	Decryptor key memory backup supply. Connect V_{BATT} to V_{CCAUX} or GND if battery is not used.
RSVD	N/A	Reserved pin - do not connect.
V_{CCO}	Input	Power-supply pins for the output drivers (per bank).
V_{CCAUX}	Input	Power-supply pins for auxiliary circuits.
V_{CCINT}	Input	Power-supply pins for the internal core logic.
GND	Input	Ground.

Notes:
1. All dedicated pins (JTAG and configuration) are powered by V_{CCAUX} (independent of the bank V_{CCO} voltage).

CS144/CSG144 Chip-Scale BGA Package Specifications (0.80mm pitch)



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	~	~	1.20
A_1	0.20	~	~
A_2	0.65	~	~
D/E	12.00 BSC		
D_1/E_1	9.60 BSC		
e	0.80 BSC		
øb	0.40	0.45	0.50
bbb	~	~	0.20
ccc	~	~	0.12
ddd	~	~	0.15
eee	~	~	0.08
M	13		

NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M–1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MO–216–BAG–2 (DEPOPULATED).
4. PAD 'E5' IS FOR PAD 'A1' CORNER INDICATION.

144–BALL CHIP SCALE BGA (CS144/CSG144)

Figure 1: **CS144/CSG144 Chip-Scale BGA Package Specifications**

Table 6: **FG256/FGG256 BGA — XC2V40, XC2V80, XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V40	No Connect in XC2V80
7	IO_L45N_7	F5	NC	NC
7	IO_L43P_7	F1	NC	NC
7	IO_L43N_7	F2	NC	NC
7	IO_L06P_7	F3	NC	
7	IO_L06N_7	F4	NC	
7	IO_L04P_7	E1	NC	
7	IO_L04N_7	E2	NC	
7	IO_L03P_7/VREF_7	E3		
7	IO_L03N_7	E4		
7	IO_L02P_7/VRN_7	D2		
7	IO_L02N_7/VRP_7	D3		
7	IO_L01P_7	D1		
7	IO_L01N_7	C1		
0	VCCO_0	F8		
0	VCCO_0	F7		
0	VCCO_0	E8		
1	VCCO_1	F10		
1	VCCO_1	F9		
1	VCCO_1	E9		
2	VCCO_2	H12		
2	VCCO_2	H11		
2	VCCO_2	G11		
3	VCCO_3	K11		
3	VCCO_3	J12		
3	VCCO_3	J11		
4	VCCO_4	M9		
4	VCCO_4	L10		
4	VCCO_4	L9		
5	VCCO_5	M8		
5	VCCO_5	L8		
5	VCCO_5	L7		
6	VCCO_6	K6		
6	VCCO_6	J6		

Table 7: **FG456/FGG456 BGA — XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V250	No Connect in XC2V500
1	IO_L21P_1	D16	NC	NC
1	IO_L06N_1	E16		
1	IO_L06P_1	E17		
1	IO_L05N_1	A17		
1	IO_L05P_1	B17		
1	IO_L04N_1	C17		
1	IO_L04P_1/VREF_1	D17		
1	IO_L03N_1/VRP_1	A18		
1	IO_L03P_1/VRN_1	B18		
1	IO_L02N_1	C18		
1	IO_L02P_1	D18		
1	IO_L01N_1	A19		
1	IO_L01P_1	B19		
2	IO_L01N_2	C21		
2	IO_L01P_2	C22		
2	IO_L02N_2/VRP_2	E18		
2	IO_L02P_2/VRN_2	F18		
2	IO_L03N_2	D21		
2	IO_L03P_2/VREF_2	D22		
2	IO_L04N_2	E19		
2	IO_L04P_2	E20		
2	IO_L06N_2	E21		
2	IO_L06P_2	E22		
2	IO_L19N_2	F19	NC	NC
2	IO_L19P_2	F20	NC	NC
2	IO_L21N_2	F21	NC	NC
2	IO_L21P_2/VREF_2	F22	NC	NC
2	IO_L22N_2	G18	NC	NC
2	IO_L22P_2	H18	NC	NC
2	IO_L24N_2	G19	NC	NC
2	IO_L24P_2	G20	NC	NC
2	IO_L43N_2	G21		
2	IO_L43P_2	G22		

Table 7: **FG456/FGG456 BGA — XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V250	No Connect in XC2V500
4	IO_L02N_4/D0/DIN(1)	V18		
4	IO_L02P_4/D1	V17		
4	IO_L03N_4/D2/ALT_VRP_4	W18		
4	IO_L03P_4/D3/ALT_VRN_4	Y18		
4	IO_L04N_4/VREF_4	AA18		
4	IO_L04P_4	AB18		
4	IO_L05N_4/VRP_4	W17		
4	IO_L05P_4/VRN_4	Y17		
4	IO_L06N_4	AA17		
4	IO_L06P_4	AB17		
4	IO_L19N_4	V16	NC	NC
4	IO_L19P_4	V15	NC	NC
4	IO_L21N_4	W16	NC	NC
4	IO_L21P_4/VREF_4	Y16	NC	NC
4	IO_L22N_4	AA16	NC	NC
4	IO_L22P_4	AB16	NC	NC
4	IO_L24N_4	W15	NC	NC
4	IO_L24P_4	Y15	NC	NC
4	IO_L49N_4	AA15	NC	
4	IO_L49P_4	AB15	NC	
4	IO_L51N_4	U14	NC	
4	IO_L51P_4/VREF_4	V14	NC	
4	IO_L52N_4	W14	NC	
4	IO_L52P_4	Y14	NC	
4	IO_L54N_4	AA14	NC	
4	IO_L54P_4	AB14	NC	
4	IO_L91N_4/VREF_4	U13		
4	IO_L91P_4	V13		
4	IO_L92N_4	W13		
4	IO_L92P_4	Y13		
4	IO_L93N_4	AA13		
4	IO_L93P_4	AB13		
4	IO_L94N_4/VREF_4	U12		
4	IO_L94P_4	V12		

Table 7: **FG456/FGG456 BGA — XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V250	No Connect in XC2V500
NA	VCCINT	R16		
NA	VCCINT	R7		
NA	VCCINT	H16		
NA	VCCINT	H7		
NA	VCCINT	G16		
NA	VCCINT	G15		
NA	VCCINT	G8		
NA	VCCINT	G7		
NA	VCCINT	F17		
NA	VCCINT	F6		
NA	GND	AB22		
NA	GND	AB1		
NA	GND	AA21		
NA	GND	AA2		
NA	GND	Y20		
NA	GND	Y3		
NA	GND	W19		
NA	GND	W4		
NA	GND	P14		
NA	GND	P13		
NA	GND	P12		
NA	GND	P11		
NA	GND	P10		
NA	GND	P9		
NA	GND	N14		
NA	GND	N13		
NA	GND	N12		
NA	GND	N11		
NA	GND	N10		
NA	GND	N9		
NA	GND	M14		
NA	GND	M13		
NA	GND	M12		
NA	GND	M11		

Table 9: **BG575/BGG575 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in XC2V1000	No Connect in XC2V1500
2	IO_L69P_2/VREF_2	L18	NC	
2	IO_L70N_2	K23	NC	
2	IO_L70P_2	L24	NC	
2	IO_L72N_2	K22	NC	
2	IO_L72P_2	L22	NC	
2	IO_L73N_2	L21	NC	NC
2	IO_L73P_2	L20	NC	NC
2	IO_L91N_2	M23		
2	IO_L91P_2	N24		
2	IO_L93N_2	M21		
2	IO_L93P_2/VREF_2	M22		
2	IO_L94N_2	M19		
2	IO_L94P_2	M20		
2	IO_L96N_2	M17		
2	IO_L96P_2	M18		
3	IO_L96N_3	N23		
3	IO_L96P_3	N22		
3	IO_L94N_3	N20		
3	IO_L94P_3	N21		
3	IO_L93N_3/VREF_3	N19		
3	IO_L93P_3	N18		
3	IO_L91N_3	N17		
3	IO_L91P_3	P17		
3	IO_L73N_3	P24	NC	NC
3	IO_L73P_3	R24	NC	NC
3	IO_L72N_3	R23	NC	
3	IO_L72P_3	R22	NC	
3	IO_L70N_3	P22	NC	
3	IO_L70P_3	P21	NC	
3	IO_L69N_3/VREF_3	P20	NC	
3	IO_L69P_3	P18	NC	
3	IO_L67N_3	T24	NC	
3	IO_L67P_3	U24	NC	
3	IO_L54N_3	T23		
3	IO_L54P_3	T22		

Table 10: **BG728 BGA — XC2V3000**

Bank	Pin Description	Pin Number
4	IO_L27P_4/VREF_4	AG19
4	IO_L28N_4	AB19
4	IO_L28P_4	AA19
4	IO_L30N_4	AC19
4	IO_L30P_4	AD19
4	IO_L49N_4	AE19
4	IO_L49P_4	AF19
4	IO_L51N_4	AA18
4	IO_L51P_4/VREF_4	Y18
4	IO_L52N_4	AB18
4	IO_L52P_4	AC18
4	IO_L54N_4	AD18
4	IO_L54P_4	AE18
4	IO_L67N_4	AF18
4	IO_L67P_4	AG18
4	IO_L69N_4	AA17
4	IO_L69P_4/VREF_4	Y17
4	IO_L70N_4	AB17
4	IO_L70P_4	AB16
4	IO_L72N_4	AD17
4	IO_L72P_4	AE17
4	IO_L73N_4	AF17
4	IO_L73P_4	AG17
4	IO_L75N_4	Y16
4	IO_L75P_4/VREF_4	W16
4	IO_L76N_4	AC16
4	IO_L76P_4	AD16
4	IO_L78N_4	AF16
4	IO_L78P_4	AG16
4	IO_L91N_4/VREF_4	W15
4	IO_L91P_4	Y15
4	IO_L92N_4	AB15
4	IO_L92P_4	AA15
4	IO_L93N_4	AC15
4	IO_L93P_4	AD15
4	IO_L94N_4/VREF_4	AE15

FF896 Flip-Chip Fine-Pitch BGA Package

As shown in Table 11, XC2V1000, XC2V1500, and XC2V2000 Virtex-II devices are available in the FF896 flip-chip fine-pitch BGA package. Pins in the XC2V1000, XC2V1500, and XC2V2000 devices are the same, except for the pin differences in the XC2V1000 and XC2V1500 devices shown in the No Connect columns. Following this table are the FF896 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 11: **FF896 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
0	IO_L01N_0	B27		
0	IO_L01P_0	A27		
0	IO_L02N_0	F24		
0	IO_L02P_0	E24		
0	IO_L03N_0/VRP_0	C26		
0	IO_L03P_0/VRN_0	C25		
0	IO_L04N_0/VREF_0	A26		
0	IO_L04P_0	A25		
0	IO_L05N_0	F23		
0	IO_L05P_0	F22		
0	IO_L06N_0	C24		
0	IO_L06P_0	D25		
0	IO_L19N_0	A24		
0	IO_L19P_0	B25		
0	IO_L20N_0	G22		
0	IO_L20P_0	G21		
0	IO_L21N_0	D24		
0	IO_L21P_0/VREF_0	D23		
0	IO_L22N_0	B23		
0	IO_L22P_0	B24		
0	IO_L23N_0	H21		
0	IO_L23P_0	H20		
0	IO_L24N_0	E22		
0	IO_L24P_0	E23		
0	IO_L49N_0	A22		
0	IO_L49P_0	B22		
0	IO_L50N_0	F21		
0	IO_L50P_0	F20		
0	IO_L51N_0	C23		
0	IO_L51P_0/VREF_0	C22		
0	IO_L52N_0	B20		
0	IO_L52P_0	B21		

Table 11: **FF896 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
7	IO_L04N_7	D29		
7	IO_L03P_7/VREF_7	E28		
7	IO_L03N_7	D28		
7	IO_L02P_7/VRN_7	H23		
7	IO_L02N_7/VRP_7	G23		
7	IO_L01P_7	B30		
7	IO_L01N_7	C30		
0	VCCO_0	K20		
0	VCCO_0	K19		
0	VCCO_0	K18		
0	VCCO_0	K17		
0	VCCO_0	K16		
0	VCCO_0	J21		
0	VCCO_0	J20		
0	VCCO_0	J19		
0	VCCO_0	J18		
0	VCCO_0	C18		
0	VCCO_0	B26		
1	VCCO_1	K15		
1	VCCO_1	K14		
1	VCCO_1	K13		
1	VCCO_1	K12		
1	VCCO_1	K11		
1	VCCO_1	J13		
1	VCCO_1	J12		
1	VCCO_1	J11		
1	VCCO_1	J10		
1	VCCO_1	C13		
1	VCCO_1	B5		
2	VCCO_2	R10		
2	VCCO_2	P10		
2	VCCO_2	N10		
2	VCCO_2	N9		
2	VCCO_2	N3		
2	VCCO_2	M10		
2	VCCO_2	M9		

Table 11: **FF896 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
NA	VBATT	A2		
NA	RSVD	E6		
NA	VCCAUX	AK28		
NA	VCCAUX	AK16		
NA	VCCAUX	AK3		
NA	VCCAUX	T1		
NA	VCCAUX	R30		
NA	VCCAUX	A28		
NA	VCCAUX	A15		
NA	VCCAUX	A3		
NA	VCCINT	AB22		
NA	VCCINT	AB9		
NA	VCCINT	AA21		
NA	VCCINT	AA10		
NA	VCCINT	Y20		
NA	VCCINT	Y19		
NA	VCCINT	Y18		
NA	VCCINT	Y17		
NA	VCCINT	Y16		
NA	VCCINT	Y15		
NA	VCCINT	Y14		
NA	VCCINT	Y13		
NA	VCCINT	Y12		
NA	VCCINT	Y11		
NA	VCCINT	W20		
NA	VCCINT	W11		
NA	VCCINT	V20		
NA	VCCINT	V11		
NA	VCCINT	U20		
NA	VCCINT	U11		
NA	VCCINT	T20		
NA	VCCINT	T11		
NA	VCCINT	R20		
NA	VCCINT	R11		
NA	VCCINT	P20		
NA	VCCINT	P11		

Table 12: **FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
NA	GND	AP33	
NA	GND	AP32	
NA	GND	AP27	
NA	GND	AP8	
NA	GND	AP3	
NA	GND	AP2	
NA	GND	AN34	
NA	GND	AN33	
NA	GND	AN20	
NA	GND	AN15	
NA	GND	AN2	
NA	GND	AN1	
NA	GND	AM34	
NA	GND	AM32	
NA	GND	AM25	
NA	GND	AM10	
NA	GND	AM3	
NA	GND	AM1	
NA	GND	AL31	
NA	GND	AL4	
NA	GND	AK30	
NA	GND	AK23	
NA	GND	AK12	
NA	GND	AK5	
NA	GND	AJ29	
NA	GND	AJ6	
NA	GND	AH28	
NA	GND	AH21	
NA	GND	AH14	
NA	GND	AH7	
NA	GND	AG34	
NA	GND	AG27	
NA	GND	AG8	
NA	GND	AG1	
NA	GND	AF19	
NA	GND	AF16	

Table 13: **FF1517 BGA — XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V4000	No Connect in the XC2V6000
3	IO_L34N_3	AH6	NC	
3	IO_L34P_3	AJ6	NC	
3	IO_L33N_3/VREF_3	AJ8	NC	
3	IO_L33P_3	AH8	NC	
3	IO_L32N_3	AL1	NC	
3	IO_L32P_3	AM1	NC	
3	IO_L31N_3	AH7	NC	
3	IO_L31P_3	AJ7	NC	
3	IO_L30N_3	AH10		
3	IO_L30P_3	AG10		
3	IO_L29N_3	AK3		
3	IO_L29P_3	AL3		
3	IO_L28N_3	AK4		
3	IO_L28P_3	AL4		
3	IO_L27N_3/VREF_3	AJ9		
3	IO_L27P_3	AH9		
3	IO_L26N_3	AM2		
3	IO_L26P_3	AN2		
3	IO_L25N_3	AK5		
3	IO_L25P_3	AL5		
3	IO_L24N_3	AK9		
3	IO_L24P_3	AK8		
3	IO_L23N_3	AN1		
3	IO_L23P_3	AP1		
3	IO_L22N_3	AK6		
3	IO_L22P_3	AL6		
3	IO_L21N_3/VREF_3	AH12		
3	IO_L21P_3	AG12		
3	IO_L20N_3	AM3		
3	IO_L20P_3	AN3		
3	IO_L19N_3	AM4		
3	IO_L19P_3	AN4		
3	IO_L12N_3	AJ12	NC	
3	IO_L12P_3	AH11	NC	
3	IO_L11N_3	AP2	NC	
3	IO_L11P_3	AR2	NC	

Table 14: **BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000**

Bank	Pin Description	Pin Number	No Connect in XC2V2000
1	IO_L21P_1	A4	
1	IO_L20N_1	G10	
1	IO_L20P_1	G9	
1	IO_L19N_1	B6	
1	IO_L19P_1	C5	
1	IO_L06N_1	C6	
1	IO_L06P_1	D6	
1	IO_L05N_1	H9	
1	IO_L05P_1	G8	
1	IO_L04N_1	D7	
1	IO_L04P_1/VREF_1	E6	
1	IO_L03N_1/VRP_1	E8	
1	IO_L03P_1/VRN_1	E7	
1	IO_L02N_1	F8	
1	IO_L02P_1	F7	
1	IO_L01N_1	B5	
1	IO_L01P_1	B3	
2	IO_L01N_2	F5	
2	IO_L01P_2	G4	
2	IO_L02N_2/VRP_2	G6	
2	IO_L02P_2/VRN_2	H6	
2	IO_L03N_2	D3	
2	IO_L03P_2/VREF_2	E4	
2	IO_L04N_2	K10	
2	IO_L04P_2	K9	
2	IO_L05N_2	D2	
2	IO_L05P_2	E3	
2	IO_L06N_2	F4	
2	IO_L06P_2	F3	
2	IO_L19N_2	L10	
2	IO_L19P_2	M10	
2	IO_L20N_2	H7	
2	IO_L20P_2	J8	
2	IO_L21N_2	D1	
2	IO_L21P_2/VREF_2	E1	
2	IO_L22N_2	G5	
2	IO_L22P_2	H5	